

ZXTP5401G

150V, SOT223, PNP High voltage transistor

Summary

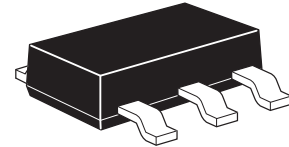
$BV_{CEO} > -150V$

$BV_{EBO} > -5V$

$I_{C(cont)} = -600mA$

$P_D = 2W$

Complementary part number ZXTN5551G

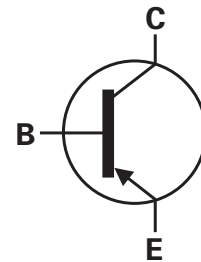


Description

A high voltage PNP transistor in a surface mount package

Features

- 150V rating
- SOT223 package

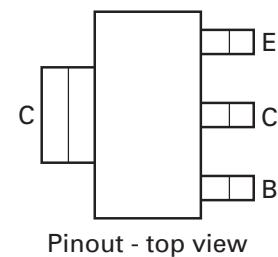


Applications

- High voltage amplification

Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP5401GTA	7	12	1000
ZXTP5401GTC	13	12	4000



Device marking

ZXTP
5401

ZXTP5401G

Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-base voltage	V_{CBO}	-160	V
Collector-emitter voltage	V_{CEO}	-150	V
Emitter-base voltage	V_{EBO}	-5	V
Continuous collector current ^(a)	I_C	-600	mA
Peak collector current	I_C	-2	A
Power dissipation at $T_A = 25^\circ\text{C}$ ^(a)	P_D	2	W
Linear derating factor		16	mW/°C
Operating and storage temperature range	T_j, T_{stg}	-55 to 150	°C

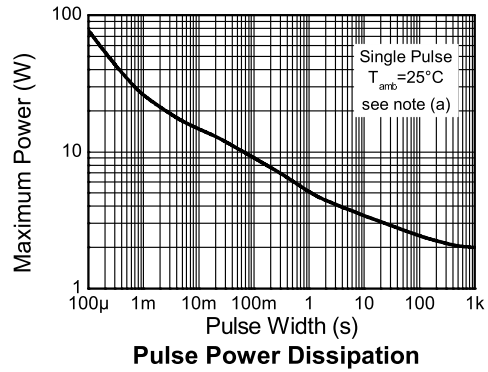
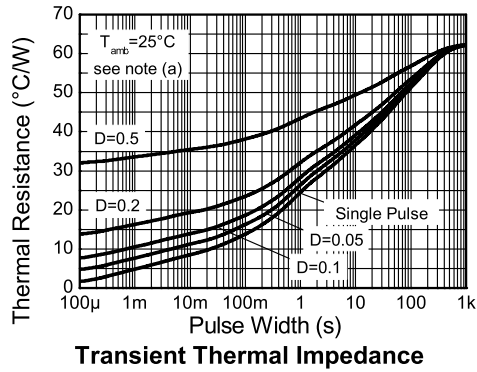
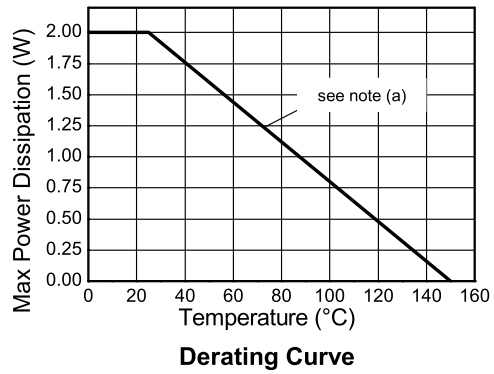
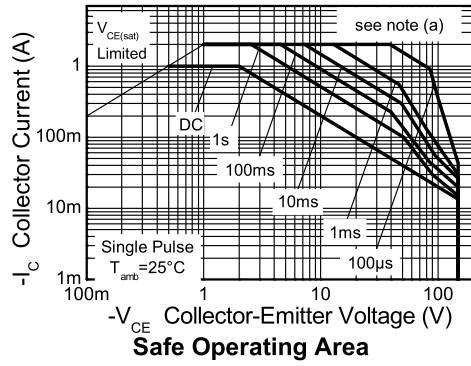
Thermal resistance

Parameter	Symbol	Limit	Unit
Junction to ambient ^(a)	$R_{\theta JA}$	62.5	°C/W

NOTES:

(a) For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 1oz weight copper, in still air conditions.

Typical characteristics

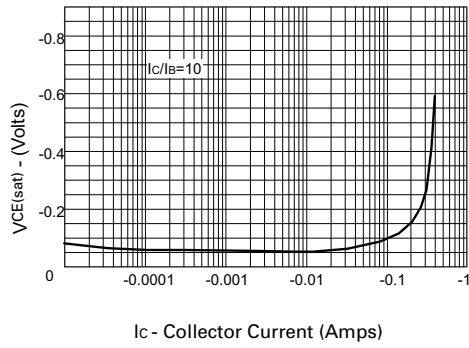


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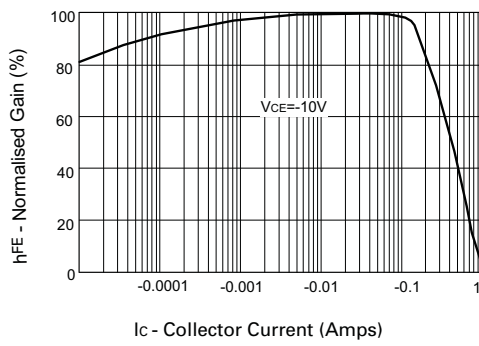
Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-base breakdown voltage	BV_{CBO}	-160	-270		V	$I_C = -100\mu\text{A}$,
Collector-emitter breakdown voltage (base open)	BV_{CEO}	-150	-240		V	$I_C = -1\text{mA}$ *
Emitter-base breakdown voltage	BV_{EBO}	-5	-8.1		V	$I_E = -10\mu\text{A}$
Collector cut-off current	I_{CBO}		<-1	-50 -50	nA μA	$V_{CB} = -120\text{V}$ $V_{CB} = -120\text{V}$, $T_{amb} = 100^{\circ}\text{C}$
Collector-emitter saturation voltage	$V_{CE(sat)}$		-50 -70	-200 -500	mV mV	$I_C = -10\text{mA}$, $I_B = -1\text{mA}$ * $I_C = -50\text{mA}$, $I_B = -5\text{mA}$ *
Base-emitter saturation voltage	$V_{BE(sat)}$		-700 -750	-1000 -1000	mV mV	$I_C = -10\text{mA}$, $I_B = -1\text{mA}$ * $I_C = -50\text{mA}$, $I_B = -5\text{mA}$ *
Static forward current transfer ratio	h_{FE}	50 60 50	135 135 130	240		$I_C = -1\text{mA}$, $V_{CE} = -5\text{V}$ * $I_C = -10\text{mA}$, $V_{CE} = -5\text{V}$ * $I_C = -50\text{mA}$, $V_{CE} = -5\text{V}$ *
Transition frequency	f_T		100		MHz	$I_C = -10\text{mA}$, $V_{CE} = -10\text{V}$ $f = 100\text{MHz}$
Output capacitance	C_{OBO}			6	pF	$V_{CB} = -10\text{V}$, $f = 1\text{MHz}$ *
Delay time	$t_{(d)}$		386		ns	$V_{CC} = -50\text{V}$. $I_C = -100\text{mA}$, $I_{B1} = I_{B2} = -10\text{mA}$.
Rise time	$t_{(r)}$		202		ns	
Storage time	$t_{(s)}$		1720		ns	
Fall time	$t_{(f)}$		275		ns	

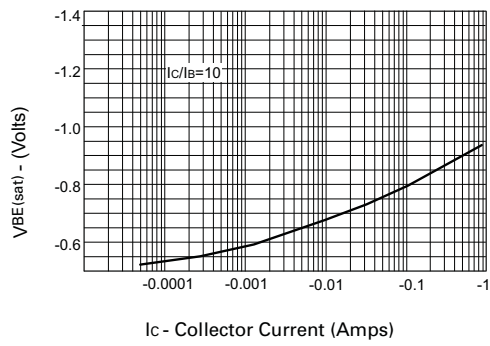
Characteristics



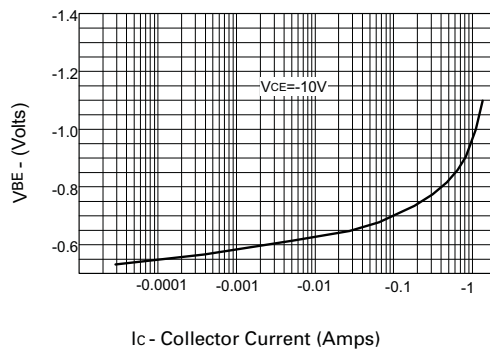
VCE(sat) v IC



hFE v IC



VBE(sat) v IC



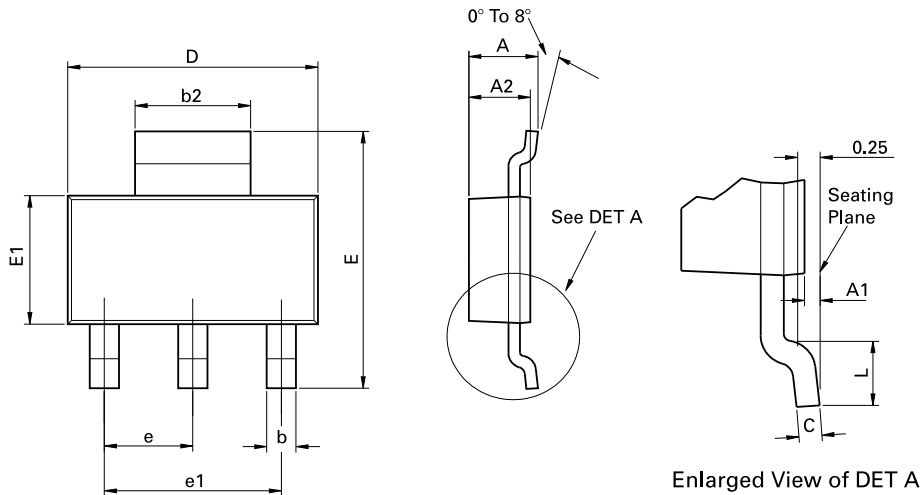
VBE(on) v IC

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Package outline - SOT223



Conforms to JEDEC TO-261 AA Issue B

Dim.	Millimeters		Inches		Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	-	1.80	-	0.071	D	6.30	6.70	0.248	0.264
A1	0.02	0.10	0.0008	0.004	e	2.30 BSC		0.0905 BSC	
A2	1.55	1.65	0.0610	0.0649	e1	4.60 BSC		0.181 BSC	
b	0.66	0.84	0.026	0.033	E	6.70	7.30	0.264	0.287
b2	2.90	3.10	0.114	0.122	E1	3.30	3.70	0.130	0.146
C	0.23	0.33	0.009	0.013	L	0.90	-	0.355	-

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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